



## Product/Process Change Notice - PCN 23\_0268 Rev. -

Analog Devices, Inc. One Analog Way, Wilmington, MA 01887, USA

This notice is to inform you of a change that will be made to certain ADI products (see Appendix A) that you may have purchased in the last 2 years. **Any inquiries or requests with this PCN (additional data or samples) must be sent to ADI within 30 days of publication date.** ADI contact information is listed below.

<b>PCN Title:</b>	Bond Wire Conversion and Mold Compound Change for ADSP-BF70x/BF70xW Processors in 184-Ball BGA Package
<b>Publication Date:</b>	23-Jan-2024
<b>Effectivity Date:</b>	26-Apr-2024 <i>(the earliest date that a customer could expect to receive changed material)</i>
<b>Revision Description:</b>	Initial Release.

### Description Of Change:

Change of bond wire material from Gold (Au) to Copper (Cu) and change of molding compound from Sumitomo G770LC to Kyocera KE G1280TS.

### Reason For Change:

Ensure continuity of supply in order to meet customer demand.

### Impact of the change (positive or negative) on fit, form, function & reliability:

There is no change to form, fit, functionality or reliability.

### Product Identification *(this section will describe how to identify the changed material)*

Change will be differentiated by date code.

### Summary of Supporting Information:

Qualification has been performed per AEC-Q100, Stress Test Qualification for Integrated Circuits. See attached Qualification Results Summary.

### Supporting Documents

**Attachment 1: Type:** Qualification Results Summary

[ADI\\_PCN\\_23\\_0268\\_Rev\\_-\\_Qualification\\_Report.pdf...](#)

**Attachment 2: Type:** Delta Qualification Matrix

[ADI\\_PCN\\_23\\_0268\\_Rev\\_-\\_Delta-Qualification-Matrix-ZVEI-5\\_0\\_16.xlsm...](#)

**Attachment 3: Type:** Detailed Change Description

[ADI\\_PCN\\_23\\_0268\\_Rev\\_-\\_184-ball\\_BGA\\_Material\\_Changes.pdf...](#)

Note: If applicable, the device material declaration will be updated due to material change.

### ADI Contact Information:

For questions on this PCN, please send an email to the regional contacts below or contact your local ADI sales representatives.

**Americas:**

**Europe:**

**Japan:**

**Rest of Asia:**



## Appendix A - Affected ADI Models:

### Added Parts On This Revision - Product Family / Model Number (26)

ADSP-BF701 / ADSP-BF701BBCZ-2	ADSP-BF701 / ADSP-BF701KBCZ-1	ADSP-BF701 / ADSP-BF701KBCZ-2	ADSP-BF701W-11 / ADBF701WCBCZ211	ADSP-BF703 / ADSP-BF703BBCZ-3
ADSP-BF703 / ADSP-BF703BBCZ-4	ADSP-BF703 / ADSP-BF703KBCZ-3	ADSP-BF703 / ADSP-BF703KBCZ-4	ADSP-BF703W-11 / ADBF703WCBCZ311	ADSP-BF703W-11 / ADBF703WCBCZ411
ADSP-BF705 / ADSP-BF705BBCZ-3	ADSP-BF705 / ADSP-BF705BBCZ-4	ADSP-BF705 / ADSP-BF705KBCZ-3	ADSP-BF705 / ADSP-BF705KBCZ-4	ADSP-BF705W-11 / ADBF705WCBCZ311
ADSP-BF705W-11 / ADBF705WCBCZ411	ADSP-BF707 / ADSP-BF707BBCZ-3	ADSP-BF707 / ADSP-BF707BBCZ-4	ADSP-BF707 / ADSP-BF707BBCZ-4RL	ADSP-BF707 / ADSP-BF707KBCZ-3
ADSP-BF707 / ADSP-BF707KBCZ-4	ADSP-BF707 / ADSPBF707BBCZ4- EGE	ADSP-BF707W-11 / ADBF707WCBCZ311	ADSP-BF707W-11 / ADBF707WCBCZ411	ADSW4000 / ADSW4000-P
ADSW4000 / ADSW4000-Y				

**Appendix B - Revision History:**

<b>Rev</b>	<b>Publish Date</b>	<b>Effectivity Date</b>	<b>Rev Description</b>
Rev. -	23-Jan-2024	26-Apr-2024	Initial Release.